



SMAF Plastic-Encapsulate Diodes

SS310LF Schottky Rectifier Diode

Features

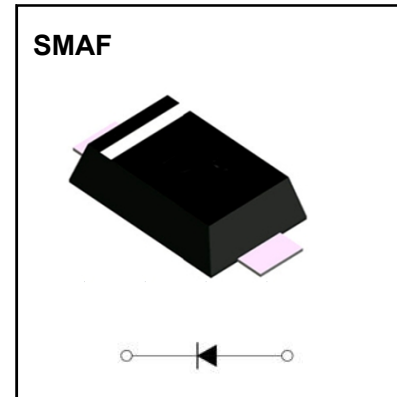
- $I_{F(AV)}$ 3A
- V_{RRM} 100V
- High surge current capability
- Polarity: Color band denotes cathode
- Low peak forward voltage

Applications

- Rectifier

Marking

- SS310L:SS310L



Limiting Values(Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	SS310LF
Repetitive Peak Reverse Voltage	V_{RRM}	V		100
Maximum RMS Voltage	V_{RMS}	V		70
Maximum DC Blocking Voltage	V_{DC}	V		100
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load, $T_L=100^\circ\text{C}$	3.0
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave, 1 cycle, $T_a=25^\circ\text{C}$	100
Junction Temperature	T_J	$^\circ\text{C}$		-55 ~ +150
Storage Temperature	T_{STG}	$^\circ\text{C}$		-55 ~ +150

Electrical Characteristics (T=25 $^\circ\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		SS310LF
Peak Forward Voltage	V_F	V	$I_F=3.0\text{A}$	$T_a=25^\circ\text{C}$	0.55 (TYP) 0.60(MAX)
Maximum Peak Reverse Current	I_{RRM1}	mA	$V_{RM}=V_{RRM}$	$T_a=25^\circ\text{C}$	0.1
	I_{RRM2}			$T_a=100^\circ\text{C}$	10
Thermal Resistance(Typical)	$R_{\theta J-A}$	$^\circ\text{C}/\text{W}$	Between junction and ambient		55
	$R_{\theta J-L}$		Between junction and lead		17

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

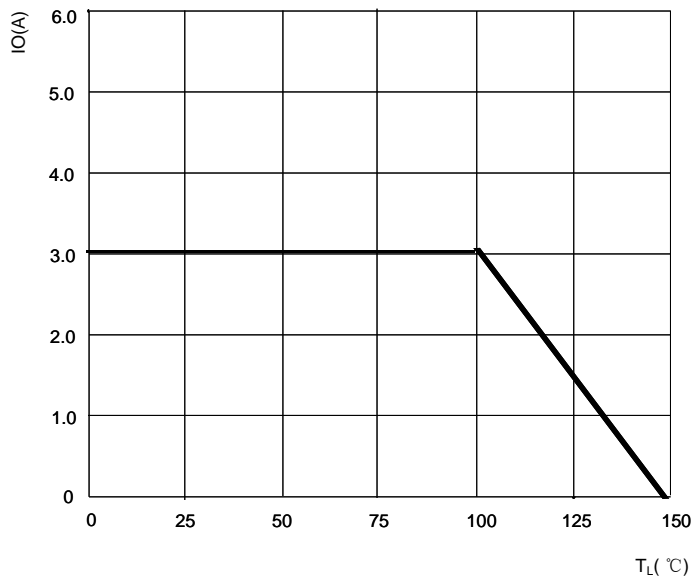


FIG.2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

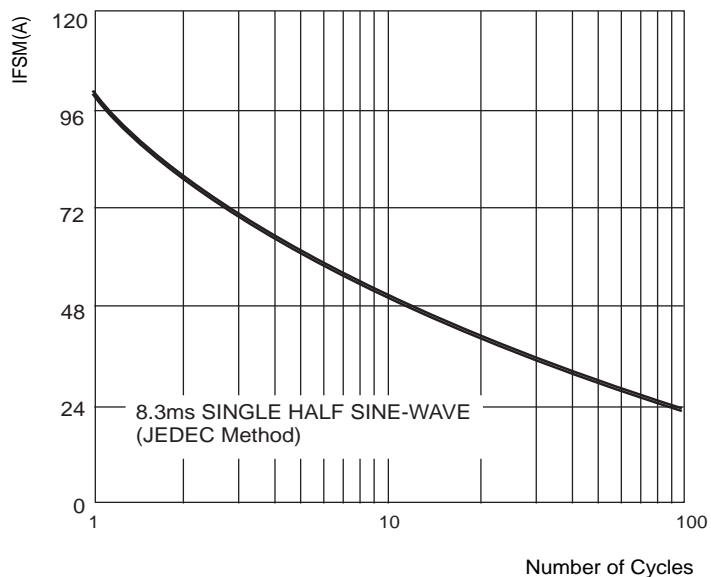


FIG.3: TYPICAL FORWARD CHARACTERISTICS

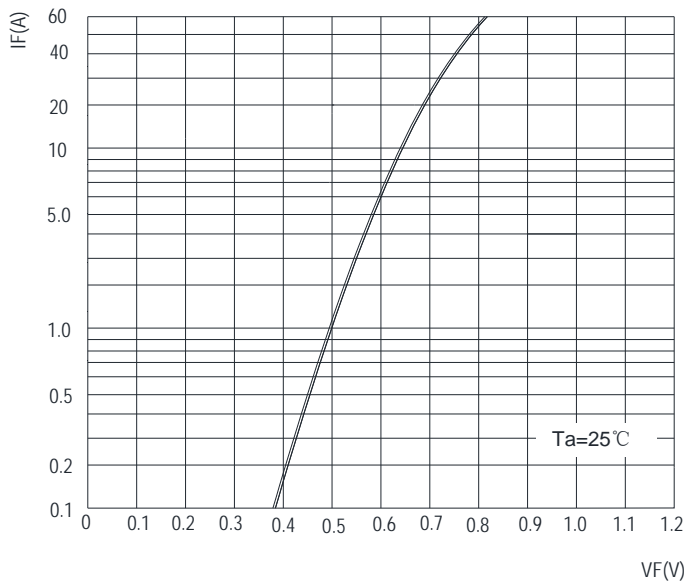
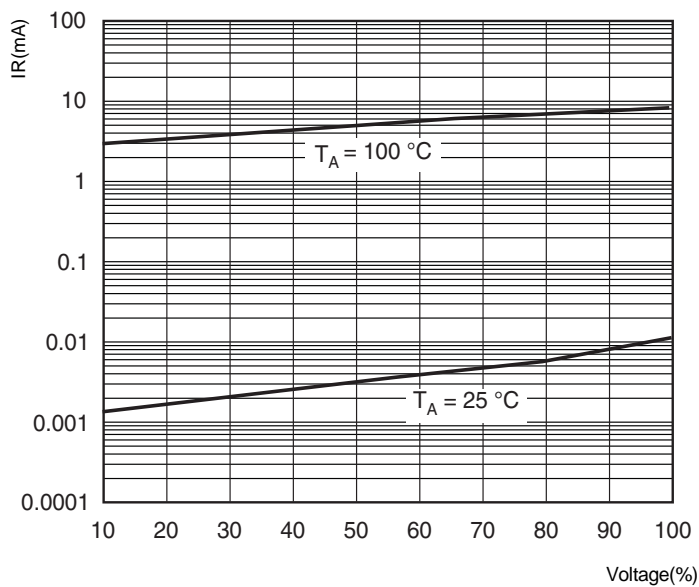
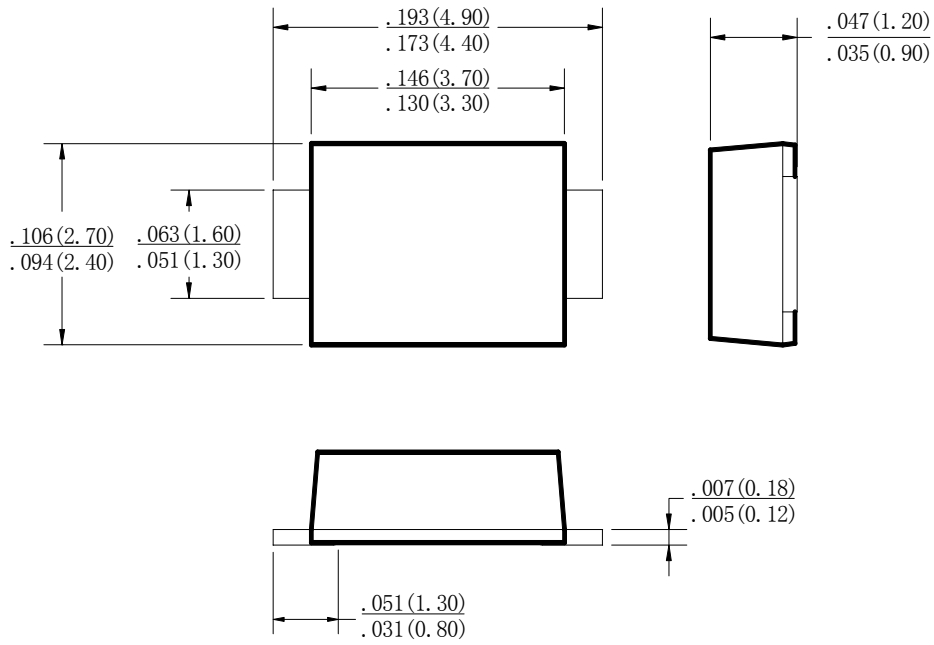


FIG.4: TYPICAL REVERSE CHARACTERISTICS

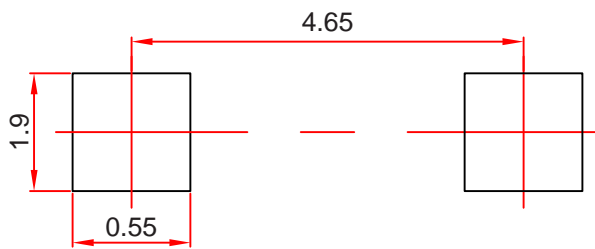


SMAF Package Outline Dimensions



Dimensions in inches and (millimeters)

SMAF Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

Reel Taping Specifications For Surface Mount Devices-SMAF

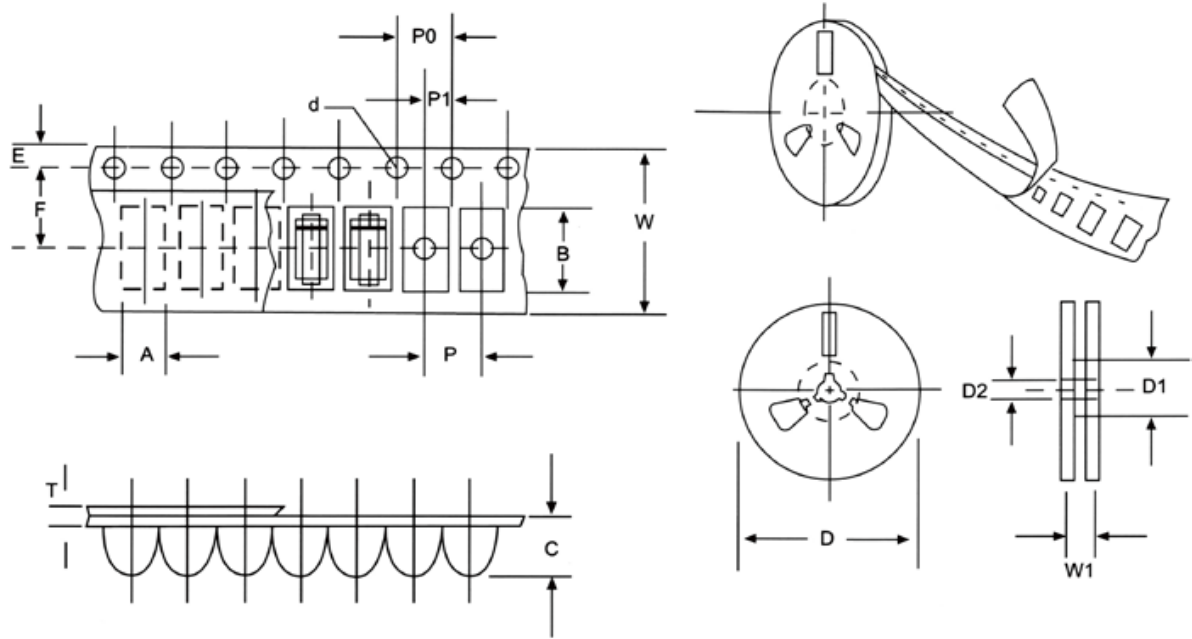


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMAF mm(inch)
Carrier width	A	2.83+0.1(0.112+0.004)
Carrier length	B	4.90+0.1(0.193+0.004)
Carrier depth	C	1.45+0.1(0.057+0.004)
Sprocket hole	d	1.55+0.05(0.061+0.002)
Reel outside diameter	D	178+2.0(7.0+0.079)
Reel inner diameter	D1	54±1.0(2.13±0.039)
Feed hole diameter	D2	13+0.5(0.512+0.020)
Sprocket hole position	E	1.75+0.1(0.069+0.004)
Punch hole position	F	5.5+0.05(0.217+0.002)
Punch hole pitch	P	4.0+0.1(0.157+0.004)
Sprocket hole pitch	P0	4.0+0.1(0.157+0.004)
Embossment center	P1	2.0+0.1(0.079+0.004)
Total tape thickness	T	0.23-0.29(0.009-0.011)
Tape width	W	12.0+0.1(0.472+0.004)
Reel width	W1	16.8+2.0(0.661+0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.